2025-02-13(목), 09:00-10:45
좌장: 추후업데이트 예정

A. Interconnect & Package 분과

[TD1-A] Emerging Interconnect 1

TD1-A-1 09:00-09:15	**Frequency Dependency of Cu Flexible Ilterconnects in Cracking Behavior during Bending Fatigue** Jun Hyeok Hyun[1], Seongi Lee[2], and Sung-Jae Choi[2], Young-Chang Joo[1], So-Yeon Lee[2] [1]School of Material Science and Engineering, Kumoh National Institute of Technology, [2]Department of Materials Science & Engineering, Seoul National University
TD1-A-2 09:15-09:30	**열처리 온도에 따른 Ru/SiGe 계면에서의 반응을 통한 접촉저항 공정 평가** 정회윤[1,4], 김성준[2,4], 박준형[1,4], 이태호[4], 박인성[3,4], 신왕철[1,4], 박영욱[1], 안진호[1,2,4] [1]한양대학교 신소재공학과, [2]한양대학교 나노반도체공학과, [3]한양대학교 나노과학기술연구소
TD1-A-3 09:30-09:45	**Influence of Oxygen/Carbon Ration on Low-k SiCOH Film Deposited by PECVD Using a Novel $C_5H_{16}OSi$ Precursor** Sangwoo Lee[1], Joonbong Lee[1], Hyunbin Chung[1], Dae Haa Ryu[1], Heeseo Yun[1], Taekjib Choi[1], Jaejin Hwang[2], Jaekwang Lee[2], In Gyu Choi[3], Hyojun Jung[3], Kwangwoo Lee[3], Sanghak Yeo[3], Sungwoo Lee[3], Jaeyoung Yang[3], Ho Jung Jeon[4], and You Seung Rim[4] 1Hybrid Materials Research Center, Department of Nanotechnology and Advanced Materials Engineering, Sejong University, 2Department of Physics, Pusan National University, 3Research and development laboratory, TES, 4Department of Semiconductor Systems Engineering and Convergence Engineering for Intelligent Drone, Sejong University
TD1-A-4 09:45-10:00	**나노 초 그린 레이저 어닐링을 활용한 Contact/via 접촉 불량 해소** 정재중[1], 박영근[1], 김영준[1], 김희태[1], 김동빈[1], 조희재[2], 권수현[2], 조병진[1] [1]한국과학기술원 전기및전자공학부, [2]나노종합기술원 나노공정기술실
TD1-A-5 10:00-10:15	**초미세 반도체 소자용 후면 전력 공급 기술(BSPDN) 특허 출원 동향** 방기인, 인치복, 김희태 특허청 반도체심사추진단

초청 TD1-A-6 10:15-10:45	Atomic Layer Deposition of Platinum Group Metals for Next-Generation Interconnects Minsu Kim Kyonggi University